

**Electronic Assembly With Sandwiched Capacitors  
And Methods of Manufacture**

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**Abstract of the Disclosure**

10 To provide high-speed, low inductance capacitive decoupling, an integrated  
circuit (IC) package includes capacitors positioned within the mounting region  
between a die and an IC package substrate. A variety of types and sizes of  
capacitors and substrates can be employed in a variety of geometrical arrangements.  
In some embodiments, capacitors are sandwiched between die terminals or bumps  
and the substrate conductors or pads, while in other embodiments, capacitors are  
15 positioned between bar-type conductors on the surface of the IC package substrate.  
Methods of fabrication, as well as application of the package to an electronic  
assembly and to an electronic system, are also described.

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